The 2026 IEEE/JSAP Symposium on VLSI Technology & Circuits Announces Call for Papers on the Theme: "Advancing the AI Frontier through VLSI Innovation"

HONOLULU, HI (October 15, 2025) – Delivering a unique convergence of technology and circuits that maximizes the synergy across both domains in the microelectronics industry for 45 years, the 2026 IEEE/JSAP Symposium on VLSI Technology & Circuits has announced a call for papers on the theme: "Advancing the AI Frontier through VLSI Innovation." The five-day in-person event's live sessions will be held at the Hilton Hawaiian Village, Honolulu, HI, from June 14 – 18, 2026, with on-demand access to technical sessions starting the following week. The Symposium will feature the latest VLSI technology developments and innovative circuit design, as well as the applications they enable, such as artificial intelligence, machine learning, IoT, wearable/implantable biomedical applications, big data, cloud/edge computing, virtual reality (VR)/augmented reality (AR), robotics, and autonomous vehicles.

The Symposium paper submission site will open on December 2, 2025, and the deadline for paper submissions is January 26, 2026 at 23:59 PST. Deadline for Late News paper submissions is March 30, 2026. Complete details for paper submission can be found online here.

The **IEEE Symposium on VLSI Technology & Circuits** seeks papers focusing on technical innovations in the following areas:

- Advanced CMOS Platforms, Interconnect & Backside Power Delivery Network (BSPDN) Technologies
- Advanced Packaging, Chiplet & Heterogeneous Integration Technologies Including 2.5D & 3D
- Analog and Mixed-Signal Circuits
- Beyond CMOS Devices That Utilize New Physics Including Spin, Optical & Quantum Computing
- Biomedical Devices, Circuits & Systems
- Computing/Processing In Memory
- Data Converters
- Device Physics, Characterization, Modeling & Reliability
- Devices & Accelerators For ML/DL & New Compute
- Digital Circuits, Hardware Security, Signal Integrity & I/Os
- DTCO & Design Enablement
- Frequency Generation & Clocking Circuits
- Memory Technologies, Devices, Circuits & Architectures
- Power Management Devices & Circuits
- Processes & Materials for CMOS Scaling & New Devices
- Processors & SoCs
- Sensors, Imagers, IoT, MEMS, Display Circuits

- Wireless and RF Devices, Circuits & Systems
- Wireline & Optical Transceivers, Optical Interconnects, & Processors

In addition to its comprehensive technical sessions, the Symposium program will feature a a series of plenary sessions by invited speakers, a demonstration session for outstanding papers, evening panel discussions, joint focus sessions, Short Courses, and workshops on relevant topics, continuing the Symposium's reputation as the microelectronics industry's premier international conference integrating technology, circuits, and systems with a range and scope unlike any other event.

The prestigious Best Student Paper Awards for each track of the Symposium are chosen based on the quality of papers and presentations. The recipients receive a monetary award, travel cost support, and a certificate. The lead author and presenter of the paper must be enrolled as a full-time student at the time of submission. In addition, extended versions of outstanding Symposium papers will be invited for publication in IEEE Transaction on Electron Devices, IEEE Journal of Solid-State Circuits, and IEEE Solid-State Circuits Letters.

Further Information and Official Call for Papers
Visit: http://www.vlsisymposium.org.

Sponsoring Organizations
The IEEE/JSAP Symposium on VLSI Technology & Circuits is sponsored by the Institute of Electrical and Electronics Engineers (IEEE) Electron Devices Society and the Solid-State Circuits Society, in cooperation with the Japan Society of Applied Physics (JSAP).

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